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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/718,932	11/22/2000	Mark Pavier	IR-17732-2498	2141

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NEW YORK, NY 100368403

EXAMINER

ROMAN, ANGEL

ART UNIT	PAPER NUMBER
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2812

DATE MAILED: 09/29/2003

Please find below and/or attached an Office communication concerning this application or proceeding.

Advisory Action

Application No.

09/718,932

Applicant(s)

PAVIER, MARK

Examiner

Angel Roman

Art Unit

2812

--The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

THE REPLY FILED 18 August 2003 FAILS TO PLACE THIS APPLICATION IN CONDITION FOR ALLOWANCE. Therefore, further action by the applicant is required to avoid abandonment of this application. A proper reply to a final rejection under 37 CFR 1.113 may only be either: (1) a timely filed amendment which places the application in condition for allowance; (2) a timely filed Notice of Appeal (with appeal fee); or (3) a timely filed Request for Continued Examination (RCE) in compliance with 37 CFR 1.114.

PERIOD FOR REPLY [check either a) or b)]

- a) ☒ The period for reply expires 3 months from the mailing date of the final rejection.
- b) ☐ The period for reply expires on: (1) the mailing date of this Advisory Action, or (2) the date set forth in the final rejection, whichever is later. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the mailing date of the final rejection.
- ONLY CHECK THIS BOX WHEN THE FIRST REPLY WAS FILED WITHIN TWO MONTHS OF THE FINAL REJECTION. See MPEP 706.07(f).

Extensions of time may be obtained under 37 CFR 1.136(a). The date on which the petition under 37 CFR 1.136(a) and the appropriate extension fee have been filed is the date for purposes of determining the period of extension and the corresponding amount of the fee. The appropriate extension fee under 37 CFR 1.17(a) is calculated from: (1) the expiration date of the shortened statutory period for reply originally set in the final Office action; or (2) as set forth in (b) above, if checked. Any reply received by the Office later than three months after the mailing date of the final rejection, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

1. ☐ A Notice of Appeal was filed on _____. Appellant's Brief must be filed within the period set forth in 37 CFR 1.192(a), or any extension thereof (37 CFR 1.191(d)), to avoid dismissal of the appeal.
2. ☐ The proposed amendment(s) will not be entered because:
- (a) ☐ they raise new issues that would require further consideration and/or search (see NOTE below);
- (b) ☐ they raise the issue of new matter (see Note below);
- (c) ☐ they are not deemed to place the application in better form for appeal by materially reducing or simplifying the issues for appeal; and/or
- (d) ☐ they present additional claims without canceling a corresponding number of finally rejected claims.

NOTE: _____

3. ☐ Applicant's reply has overcome the following rejection(s): _____.
4. ☐ Newly proposed or amended claim(s) _____ would be allowable if submitted in a separate, timely filed amendment canceling the non-allowable claim(s).
5. ☒ The a) ☐ affidavit, b) ☐ exhibit, or c) ☒ request for reconsideration has been considered but does NOT place the application in condition for allowance because: See Continuation Sheet.
6. ☐ The affidavit or exhibit will NOT be considered because it is not directed SOLELY to issues which were newly raised by the Examiner in the final rejection.
7. ☒ For purposes of Appeal, the proposed amendment(s) a) ☒ will not be entered or b) ☐ will be entered and an explanation of how the new or amended claims would be rejected is provided below or appended.

The status of the claim(s) is (or will be) as follows:

Claim(s) allowed: _____

Claim(s) objected to: _____

Claim(s) rejected: 1,2 and 5-12

Claim(s) withdrawn from consideration: _____

8. ☐ The proposed drawing correction filed on _____ is a) ☐ approved or b) ☐ disapproved by the Examiner.
9. ☐ Note the attached Information Disclosure Statement(s) (PTO-1449) Paper No(s). _____
10. ☐ Other: _____

Continuation of 5. does NOT place the application in condition for allowance because: The arguments with respect to claims 1-2 and 5-12 are not convincing. Applicants argue that Umehara U.S. Patent No. 5,882,956 teaches partially curing the polyimide layer 4 when the polyimide bonding sheet 7 is formed by attaching polyimide layer 4 to polyimide resin 3 before polyimide layer 4 is attached to the wafer 6 and that this is supported by the fact that Umehara suggest rather high temperatures (up to 300 degrees Celsius, column 6, lines 55-57) for the wafer thermocompression bonding process. Applicants also argue that claims 1 and 12 call for simply laying the polyimide film on the wafer, rather than pressing the polyimide film as taught by Umehara. With respect to Applicant's arguments that the polyimide film in the Umehara reference is partially cured when is bonded to the wafer, Umehara suggest preferable temperatures of 120-150 degrees Celsius for thermocompressing bonding the polyimide layer to the wafer (see column 6, lines 57-58) and a temperature of 150-250 degrees Celsius for curing the polyimide layer when it is disposed on a lead frame (see column 7, lines 42-47), therefore the polyimide layer 4 can't be in a fully cured state after the thermocompression bonding process and the temperature treatment during the thermocompression bonding can be considered as having a partial curing effect on the polyimide layer 4. Regarding simply laying the polyimide layer rather than pressing the layer, Umehara teaches a thermocompressing bonding process for bonding the polyimide layer to the wafer, in order to bond a layer using thermocompressing bonding the layer has to be laid first, therefore Umehara also teaches laying the polyimide on the wafer as claimed by Applicants.

